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### 1-1825109-2 Product Details

### Have a Question?

Chat with a Product Information Specialist





### **DIP Sockets**

Always EU RoHS/ELV Compliant (Statement of Compliance)

### Product Highlights:

- Socket Style = Standard Through Hole Contact Termination Type 2.54 mm Centerline

View all Features

- Row-to-Row Spacing = 15.49 mm
- 28 Positions





### **Quick Links**

- Check Pricing & Availability
- Search for Tooling
- Product Feature Selector
  Contact Us About This Product

TE Internal Number: 1-1825109-2 

# Documentation & Additional Information

### Product Drawings:

### Catalog Pages/Data Sheets:

### **Product Specifications:**

Application Specifications:

• DIPLOMATE DL (Dual Leaf) DIP Sockets (PDF, English)

### Instruction Sheets:

CAD Files:
• None Available

### List all Documents

# Product Features (Please use the Product Drawing for all design activity)

# Product Type Features: • Socket Style = Standard

- Profile = Standard
- Frame Style = Ladder • Leg Style = Straight
- Proprietary Name = DIPLOMATE DL
- Color = Black
- Comment = ONLY sockets with straight solder tails are recommended for automatic insertion.

- Electrical Characteristics:
   Insulation Resistance (MΩ) = 10,000
  - Contact Resistance (mΩ) = 30

### **Termination Related Features:**

- Termination Post Length (mm [in]) = 3.25 [0.128]
- Solder Tail Contact Plating = Tin

### **Body Related Features:**

- <u>Centerline (mm [in])</u> = 2.54 [0.100]
- Row-to-Row Spacing (mm [in]) = 15.49 [0.610]
- Number of Positions = 28
- Mount Style = Vertical

### Contact Related Features:

- Contact Termination Type = Through Hole
- Contact Base Material = Beryllium Copper • Contact Plating, Mating Area, Material = Gold (30)
- Contact Style = Stamped + Formed
- Mating Contact Type = Dual Leaf

# Additional Information:

### Related Products:

## Housing Related Features:

- Housing Material = Thermoplastic GF
  - UL Flammability Rating = UL 94V-0

Configuration Related Features:

• Height Above PC Board (mm [in]) = 5.33 [0.210]

## Industry Standards:

- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- <u>Lead Free Solder Processes</u> = Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C
- · RoHS/ELV Compliance History = Always was RoHS compliant

Conditions for Usage:
• Temperature Range (°C) = 125

## Operation/Application:

### Packaging Related Features:

Packaging Method = Tube

### Other:

• Brand = Tyco Electronics

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